



Material Content Data Sheet



Sales Product Name		BAS 16-02L E6327		Issued		19. July 2018		
MA#		MA000447846						
Package		PG-TSLP-2-1		Weight*		0.52 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.07		709	
	noble metal	gold	7440-57-5	0.001	0.27		2748	
	inorganic material	silicon	7440-21-3	0.017	3.35	3.69	33535	36992
leadframe	non noble metal	nickel	7440-02-0	0.100	19.48	19.48	194801	194801
wire	noble metal	gold	7440-57-5	0.006	1.14	1.14	11412	11412
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.04		360	
	organic material	carbon black	1333-86-4	0.004	0.72		7192	
	plastics	epoxy resin	-	0.050	9.71		97107	
	inorganic material	silicondioxide	60676-86-0	0.316	61.48	71.95	614648	719307
leadfinish	noble metal	gold	7440-57-5	0.010	1.87	1.87	18744	18744
plating	noble metal	gold	7440-57-5	0.010	1.87	1.87	18744	18744
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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